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#### **HEX INVERTERS WITH OPEN DRAIN OUTPUTS**

#### **Description**

The 74LVC06A provides six independent open-drain inverter buffers. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using IOFF. The IOFF circuitry disables the output preventing damaging current backflow when the device is powered down. The outputs can be connected to implement active-low wired-OR or active-high wired-AND functions.

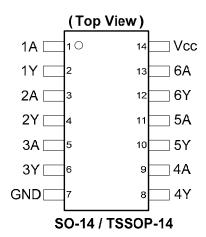
The gates perform the positive Boolean function:

$$Y = A$$

#### **Features**

- Wide Supply Voltage Range from 1.65V to 5.5V
- Sinks 24mA at V<sub>CC</sub> = 3.3V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs or Outputs Accept Up to 5.5V
- Inputs Can be Driven by 3.3V or 5.5V Allowing for Voltage Translation Applications.
- ESD Protection Exceeds JESD 22
  - 200-V Machine Model (A115-A)
  - 2000-V Human Body Model (A114-A)
  - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 250mA per JESD 78, Class II
- Range of Package Options SO-14 and TSSOP-14
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Pin Assignments**



#### **Applications**

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
  - Wide array of products such as:
    - PCs, networking, notebooks, ultrabooks, netbooks
    - Computer peripherals, hard drives, CD/DVD ROM
    - TV, DVD, DVR, set top box

Notes:

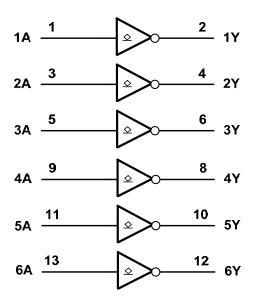
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



## **Pin Descriptions**

Pin Number	Pin Name	Description	
1	1A	Data Input	
2	1Y	Data Output	
3	2A	Data Input	
4	2Y	Data Output	
5	3A	Data Input	
6	3Y	Data Output	
7	GND	Ground	
8	4Y	Data Output	
9	4A	Data Input	
10	5Y	Data Output	
11	5A	Data Input	
12	6Y	Data Output	
13	6A	Data Input	
14	V <sub>CC</sub>	Supply Voltage	

## **Logic Diagram**



## **Function Table**

Inputs	Outputs
Α	Υ
Н	L
L	Z



## **Absolute Maximum Ratings** (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +6.5	V
VI	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage applied to output in high impedance or IOFF state	-0.5 to +6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
lıĸ	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < 0	-50	mA
lo	Continuous Output Current	50	mA
	Continuous current through Vdd or GND	±100	mA
$T_J$	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

## Recommended Operating Conditions (Note 5) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage		1.65	5.5	V	
$V_{I}$	Input Voltage		0	5.5	V	
V	Output Valtage	Active Mode	0	$V_{CC}$	V	
Vo	Output Voltage	V <sub>CC</sub> = 0V; Power Down Mode	0	5.5	V	
Λ÷/Λ\/	Innut transition rise or fall rate	V <sub>CC</sub> = 1.65V to 2.7V		20	20/1/	
Δt/ΔV	Input transition rise or fall rate	V <sub>CC</sub> = 2.7V to 5.5V		10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	+125	°C	

Notes: 5. Unused inputs should be held at  $V_{CC}$  or Ground.



## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

0		T O	.,	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$		11
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Min	Max	Min	Max	Unit
			1.65V to 1.95V	0.65 X V <sub>CC</sub>		0.65 X V <sub>CC</sub>		
	High-level Input		2.3V to 2.7V	1.7		1.6		.,
$V_{IH}$	Voltage		2.7V to 3.6V	2.0		2.0		V
			4.5V to 5.5V	0.7 X V <sub>CC</sub>		2.0		
			1.65V to 1.95V		0.35 X V <sub>CC</sub>		0.35 X V <sub>CC</sub>	
.,	Low-level input		2.3V to 2.7V		0.7		0.7	.,
$V_{IL}$	voltage		2.7V to 3.6V		0.8		0.8	V
			4.5V to 5.5V		0.3 X V <sub>CC</sub>		0.3 X V <sub>CC</sub>	
		I <sub>OL</sub> = 100μA	1.65V to 5.5V		0.2		0.3	
		I <sub>OL</sub> = 4mA	1.65V		0.45		0.6	
		I <sub>OL</sub> = 8mA	2.3V		0.70		0.85	
$V_{OL}$	Low-level Output Voltage	10	2.7V		0.40		0.6	٧
	Output Voltage	I <sub>OL</sub> = 12mA	3.0V		0.55		0.6	
		I <sub>OL</sub> = 24mA	3.0V		0.55		0.6	
		I <sub>OL</sub> = 32mA	4.5V		0.55		0.6	
l <sub>OZ</sub>	Z State Leakage Current	V <sub>O</sub> = GND or 5.5V	3.6V		±10		±20	μA
l <sub>l</sub>	Input Current	V <sub>I</sub> =GND to 5.5V	3.6V		± 5		± 20	μA
l <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 0V$ to 3.6V	0		10		20	μА
I <sub>CC</sub>	Supply Current	$V_I = GND \text{ or } V_{CC}$ $I_{O}=0$	3.6V		10		40	μA



## **Switching Characteristics**

Symbol	Doromotor	Test	V	Τį	\ = +25°	°C	-40°C to	+85°C	-40°C to	+125°C	Unit
Syllibol	bol Parameter Condition	Conditions	onditions V <sub>CC</sub>		Тур	Max	Min	Max	Min	Max	Offic
		Propagation Figure 1	1.65V to1.95V	0.3	2.9	5.3	0.3	5.6	0.3	7.6	
			2.3V to 2.7V	0.3	2.6	4.1	0.3	4.7	0.3	5.5	
t <sub>PLZ</sub> /t <sub>PZL</sub>	Propagation  Delay A <sub>N</sub> to Y <sub>N</sub>		2.7V	0.3	2.5	4.0	0.3	4.5	0.3	5.0	ns
	Delay A <sub>N</sub> to Y <sub>N</sub>	Delay AN to TN	3V to 3.6V	0.3	2.3	3.5	0.3	3.7	0.3	5.0	
			4.5V to 5.5V	0.3	1.7	2.5	0.3	3.4	0.3	4.5	

## Operating Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

	Parameter	Test	V <sub>CC</sub> = 1.8V	V <sub>CC</sub> = 2.5V	$V_{CC} = 3.3V$	V <sub>CC</sub> = 5V	Unit
	Parameter	Conditions	Тур	Тур	Тур	Тур	Oilit
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	7.0	7.5	8.0	8.6	pF
Cı	Input Capacitance	$V_I = V_{CC} - or$ GND	4	4	4	4	pF

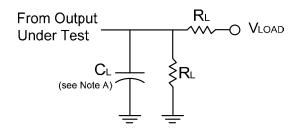
## **Package Characteristics**

Symbol	Parameter	Test Conditions	V <sub>cc</sub>	Min	Тур	Max	Unit
0	Thermal Resistance SO-14		(Note 6)		TBD		°C/W
$\theta_{JA}$	Junction-to-Ambient	TSSOP-14	(Note 6)		159		C/VV
0	Thermal Resistance	SO-14	(Note 6)		TBD		°C/W
θЈС	Junction-to-Case	TSSOP-14	(Note o)		25		

Note: 6. Test condition for SO-14 and TSSOP-14: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

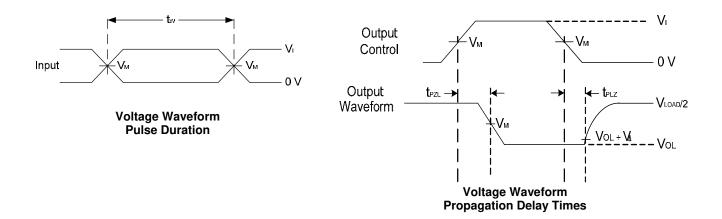


#### **Parameter Measuement Information**



TEST	Condition
t <sub>PLZ</sub> (see Note E)	$V_{LOAD}$
t <sub>PZL</sub> (see Note D)	$V_{LOAD}$

V	Inp	outs	V	V	C	В	V	
V <sub>cc</sub>	Vı	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub> V <sub>LOAD</sub>		CL	$R_L$	$oldsymbol{V}_{\Delta}$	
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	30pF	1ΚΩ	0.15V	
2.5V±0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	30pF	500Ω	0.15V	
2.7V	2.7V	≤2ns	1.5V	6V	50pF	500Ω	0.3V	
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V	
5V±0.5V	Vcc	≤2.5ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	50pF	500Ω	0.3V	



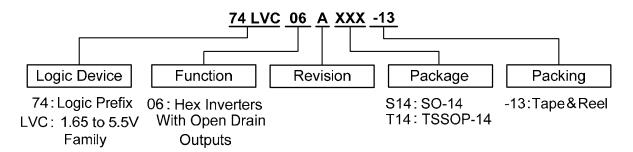
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
  C. The inputs are measured one at a time with one transition per measurement.
- D.  $t_{PZL}$  is measured at  $V_{M}$ .
- E.  $t_{PLZ}$  is measured at  $V_{OL}$  + $V_{\Delta}$ .

Figure 1. Load Circuit and Voltage Waveforms



#### **Ordering Information**

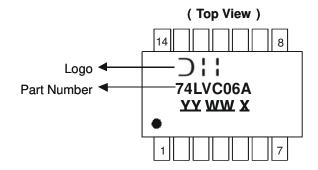


	Device	Package	Packaging	13" Tape and Reel		
	Device	Code	(Note 7)	Quantity	Part Number Suffix	
9	74LVC06AS14-13	S14	SO-14	2500/Tape & Reel	-13	
9	74LVC06AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13	

Notes: 7. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

#### **Marking Information**

#### (1) SO-14, TSSOP-14



YY: Year: 08, 09,10~ WW: Week: 01~52; 52 represents 52 and 53 week

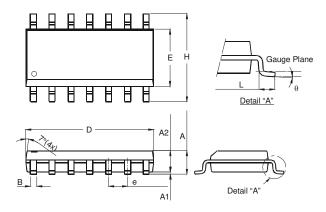
X: Internal Code

Part Number	Package
74LVC06AS14	SO-14
74LVC06AT14	TSSOP-14



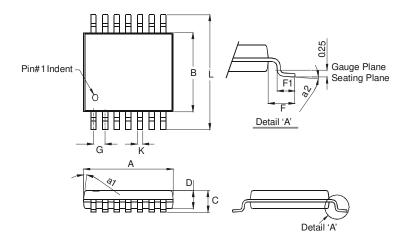
## Package Outline Dimensions (All dimensions in mm.)

#### Package Type: SO-14



SO-14		
Dim	Min	Max
Α	1.47	1.73
<b>A</b> 1	0.10	0.25
A2	1.45 Typ	
В	0.33	0.51
D	8.53	8.74
Е	3.80	3.99
е	1.27 Typ	
Н	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

#### Package Type: TSSOP-14

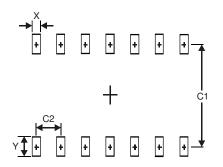


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
Α	4.9	5.10
В	4.30	4.50
С	_	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
١	6.40 Typ	
All Dimensions in mm		



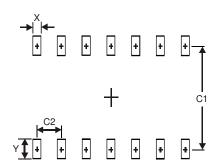
## **Suggested Pad Layout**

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Υ	1.50
C1	5.4
C2	1 27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65



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